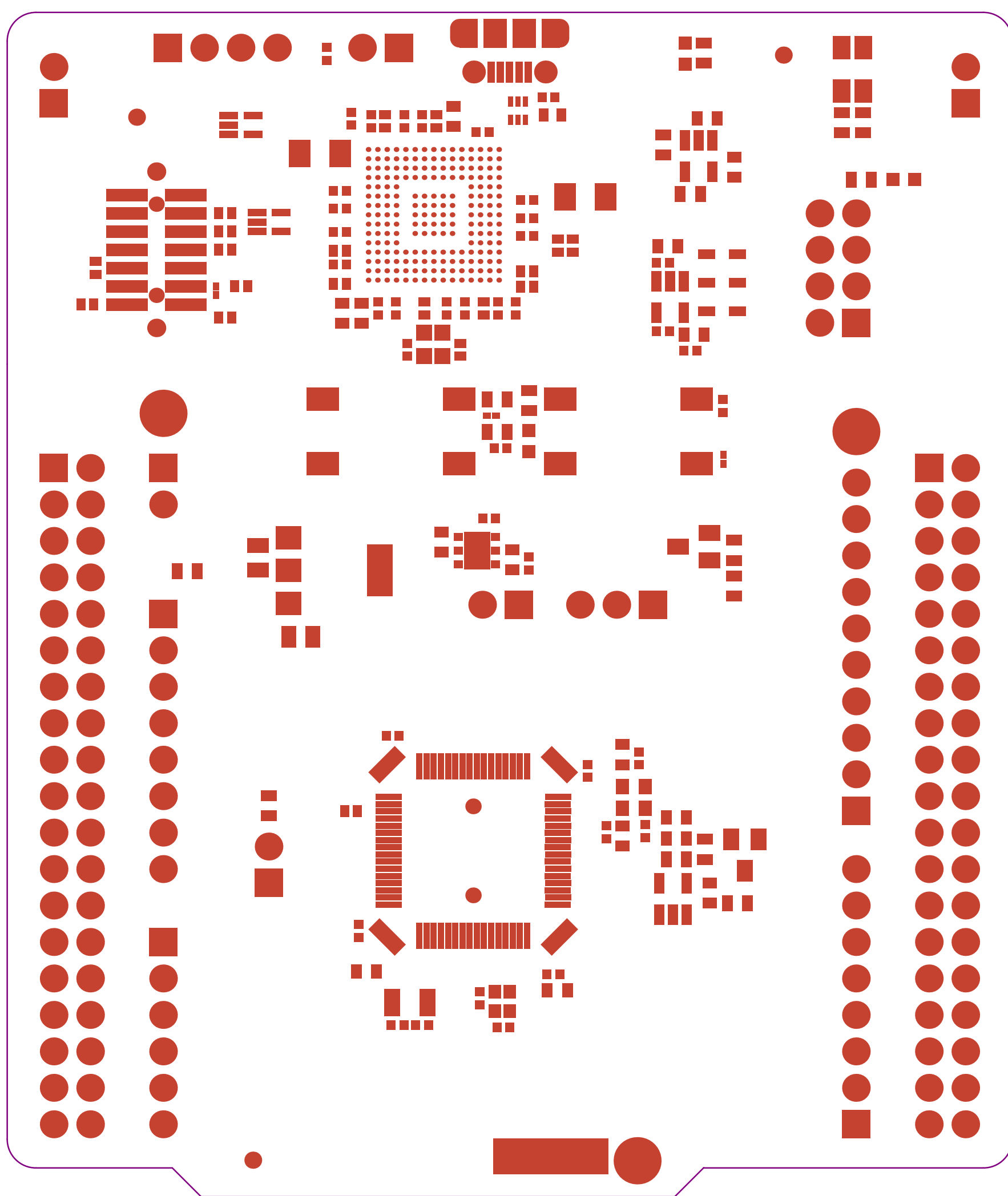


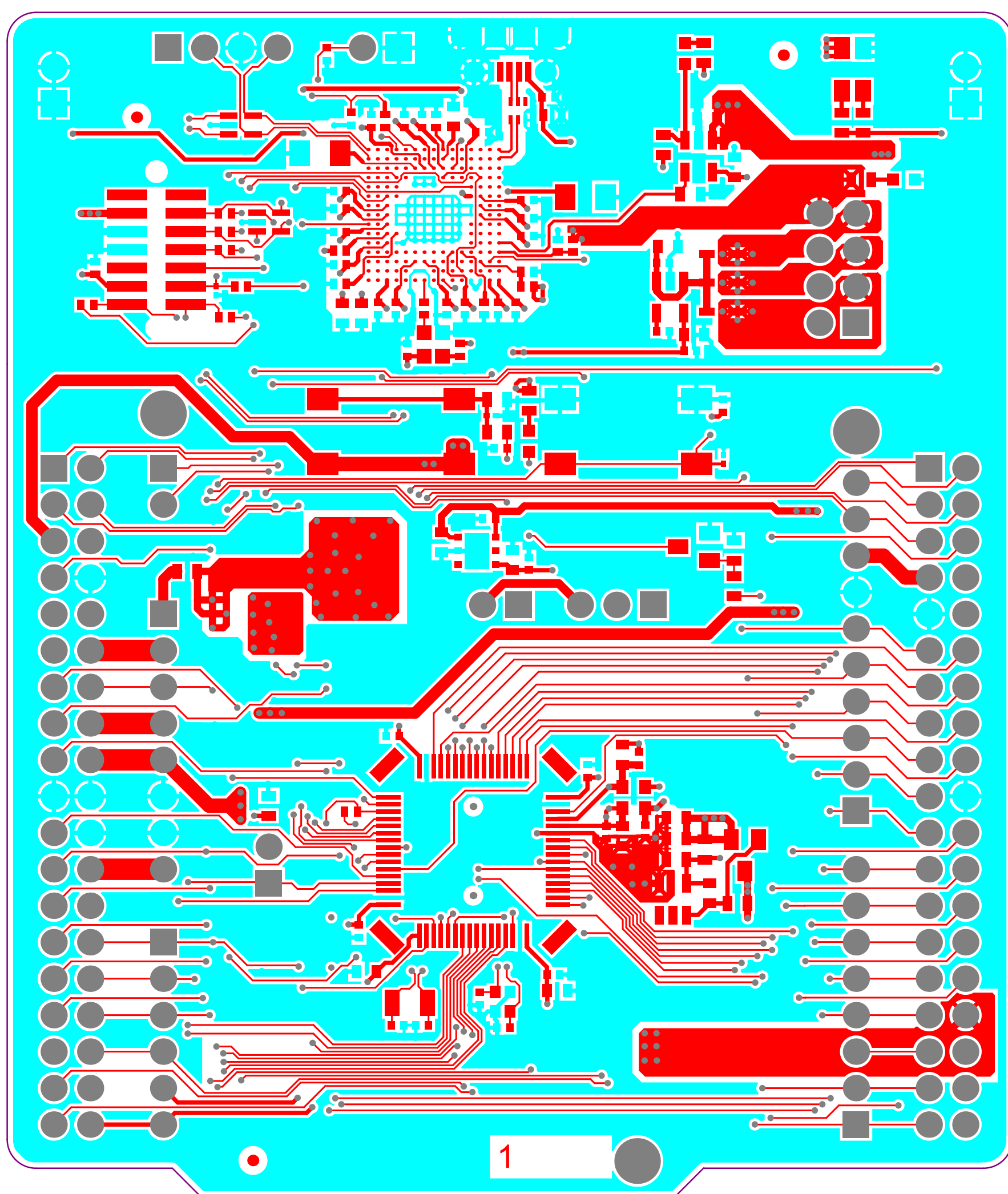
Top Overlay

.GBO



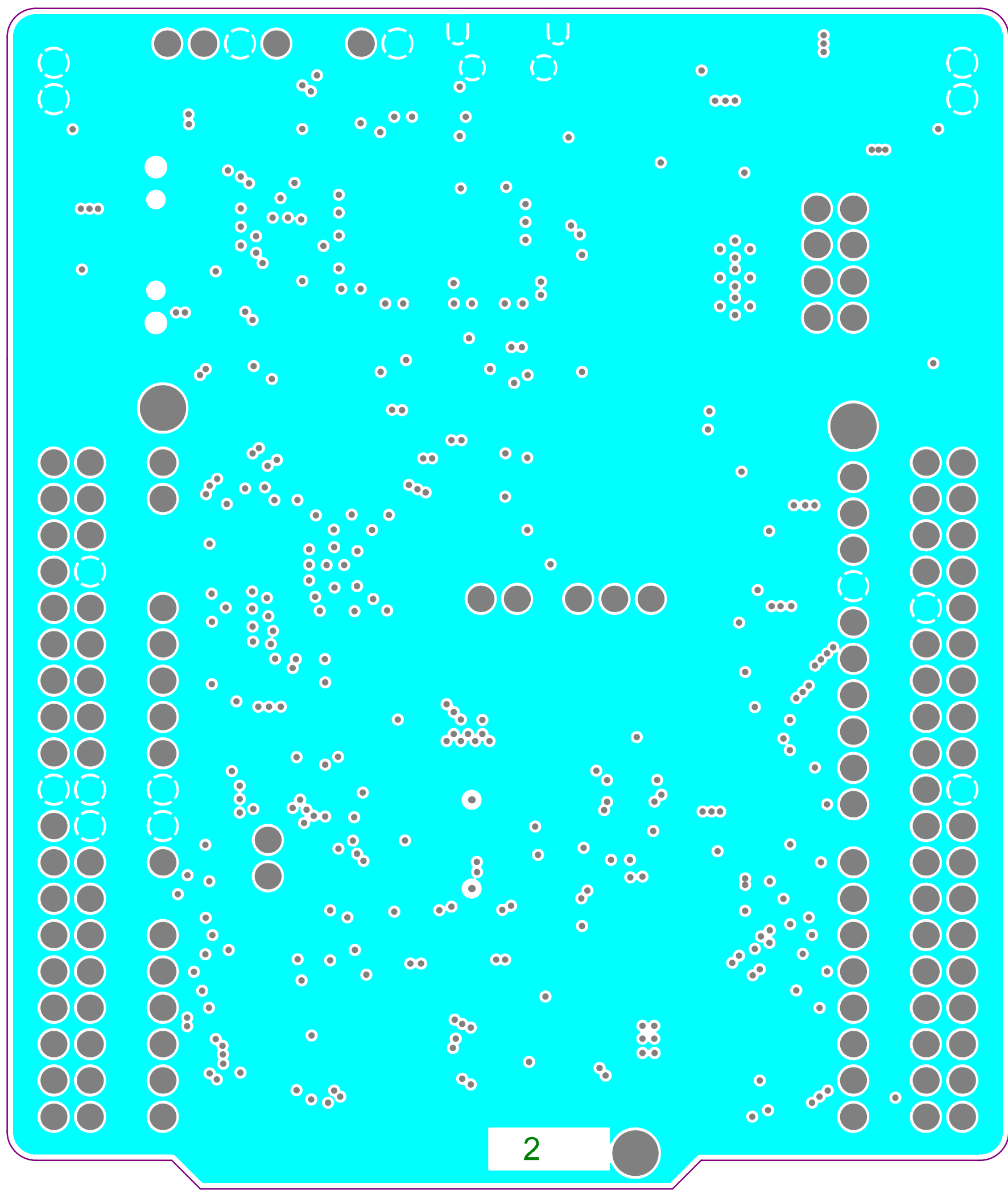
Top Solder

.GBS



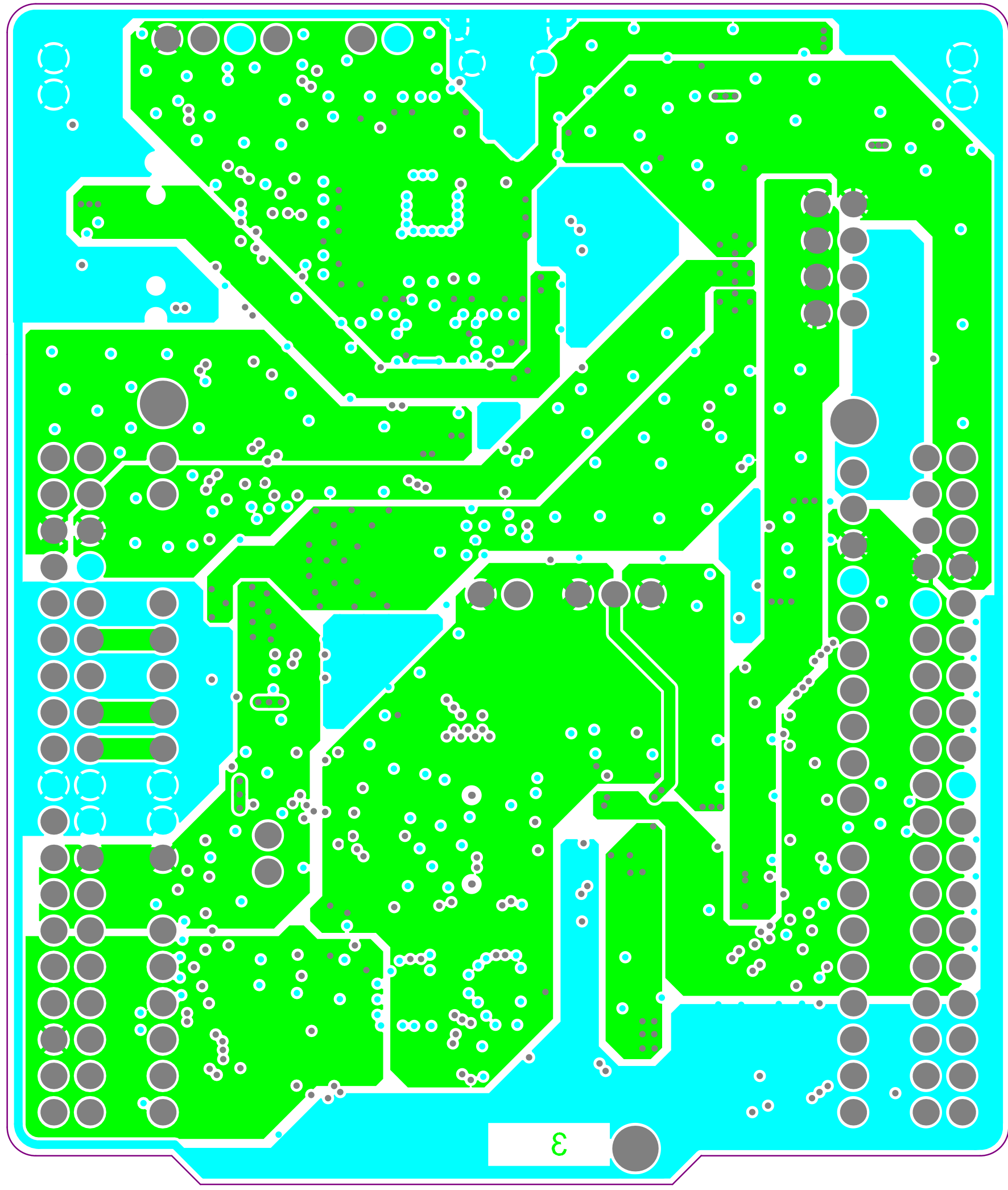
Top Layer

.GBL



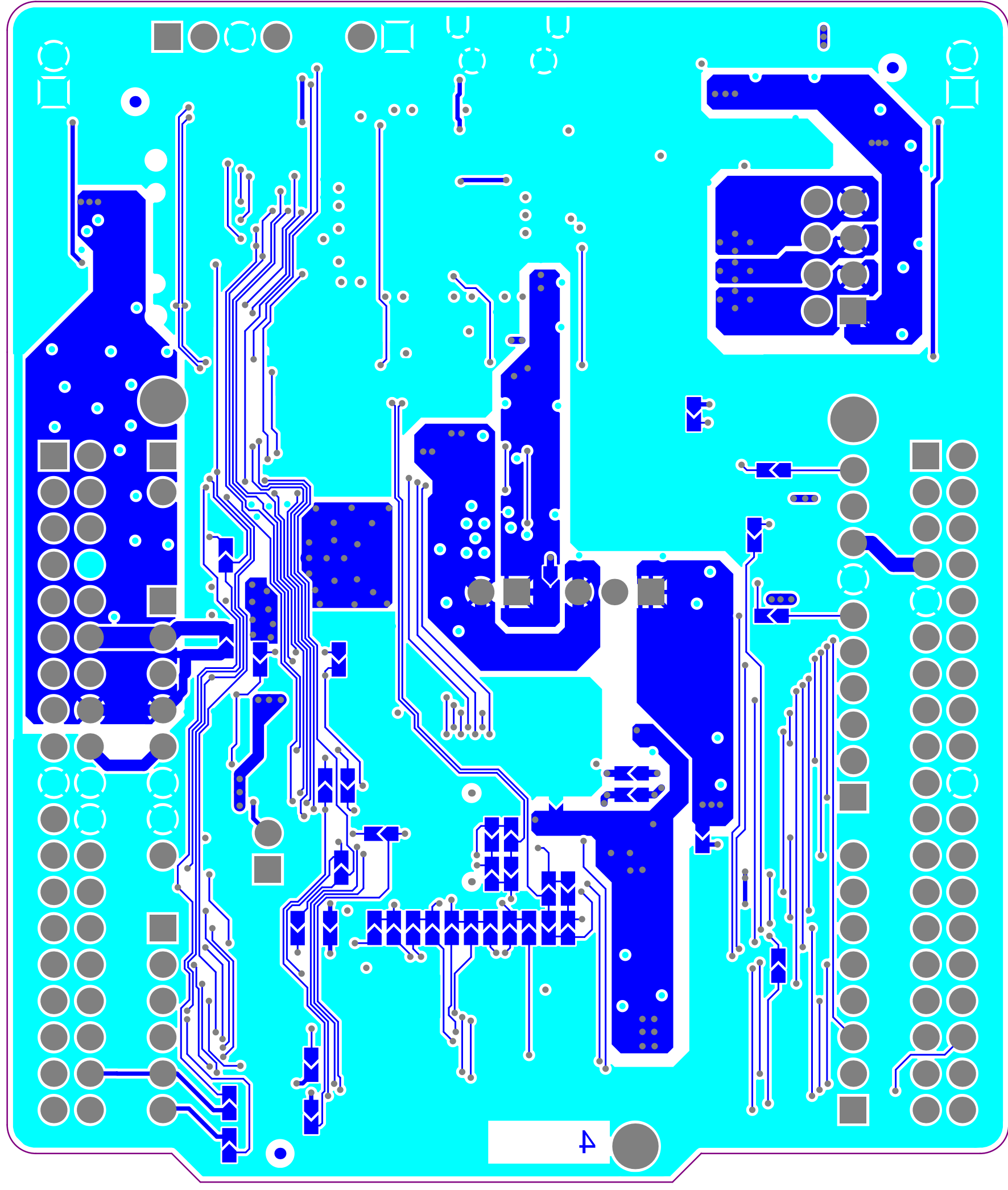
Signal Layer 2

Q2.



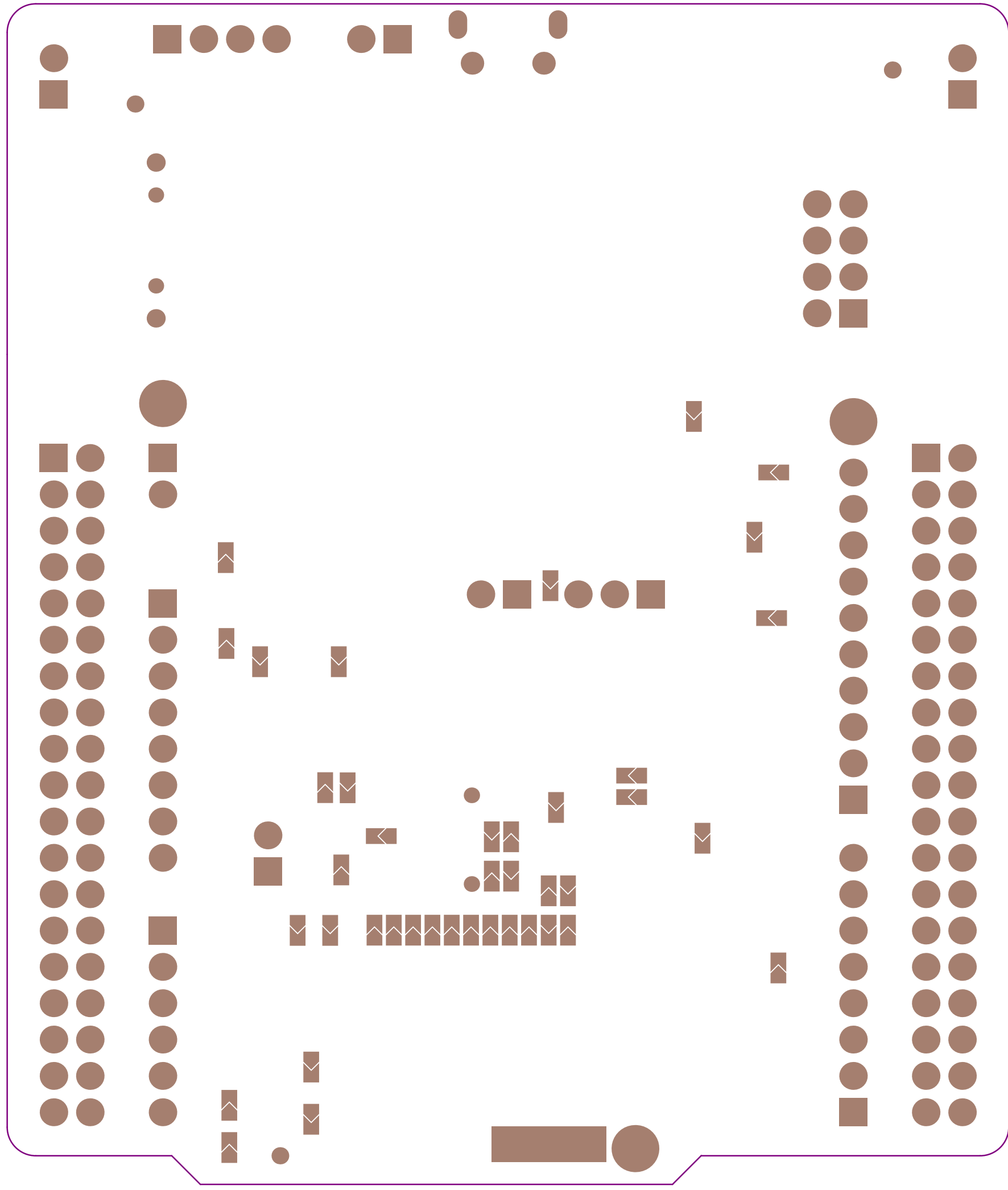
Bottom Layer

.GTL



## Bottom Solder

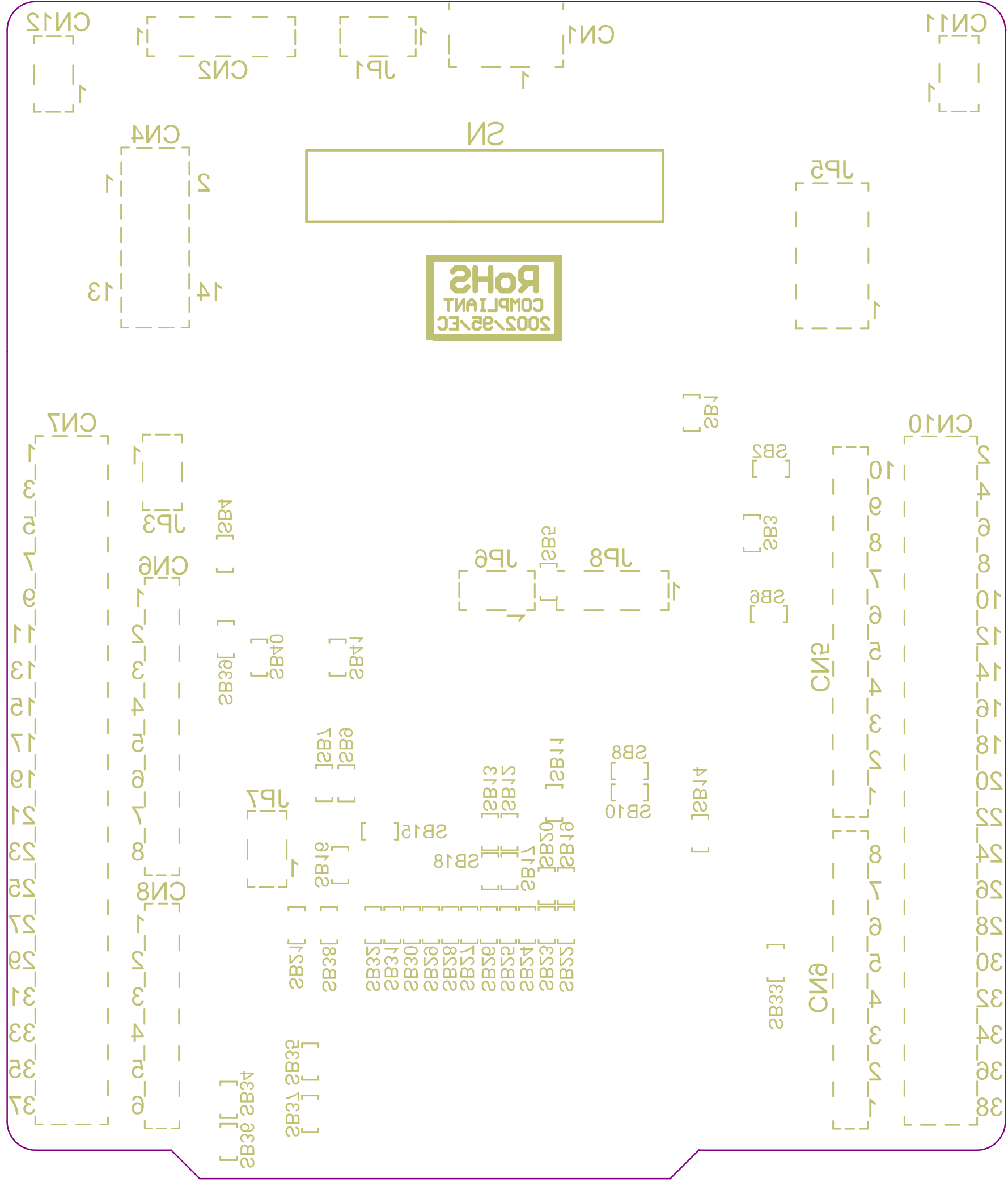
ΣΤΘ.



.GTO

Bottom Overlay

CART-1





« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ WHITE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☐ WHITE

☐ YELLOW

☐ BLACK

☒ Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.  
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

\*\*Plating type :  
lead Gold

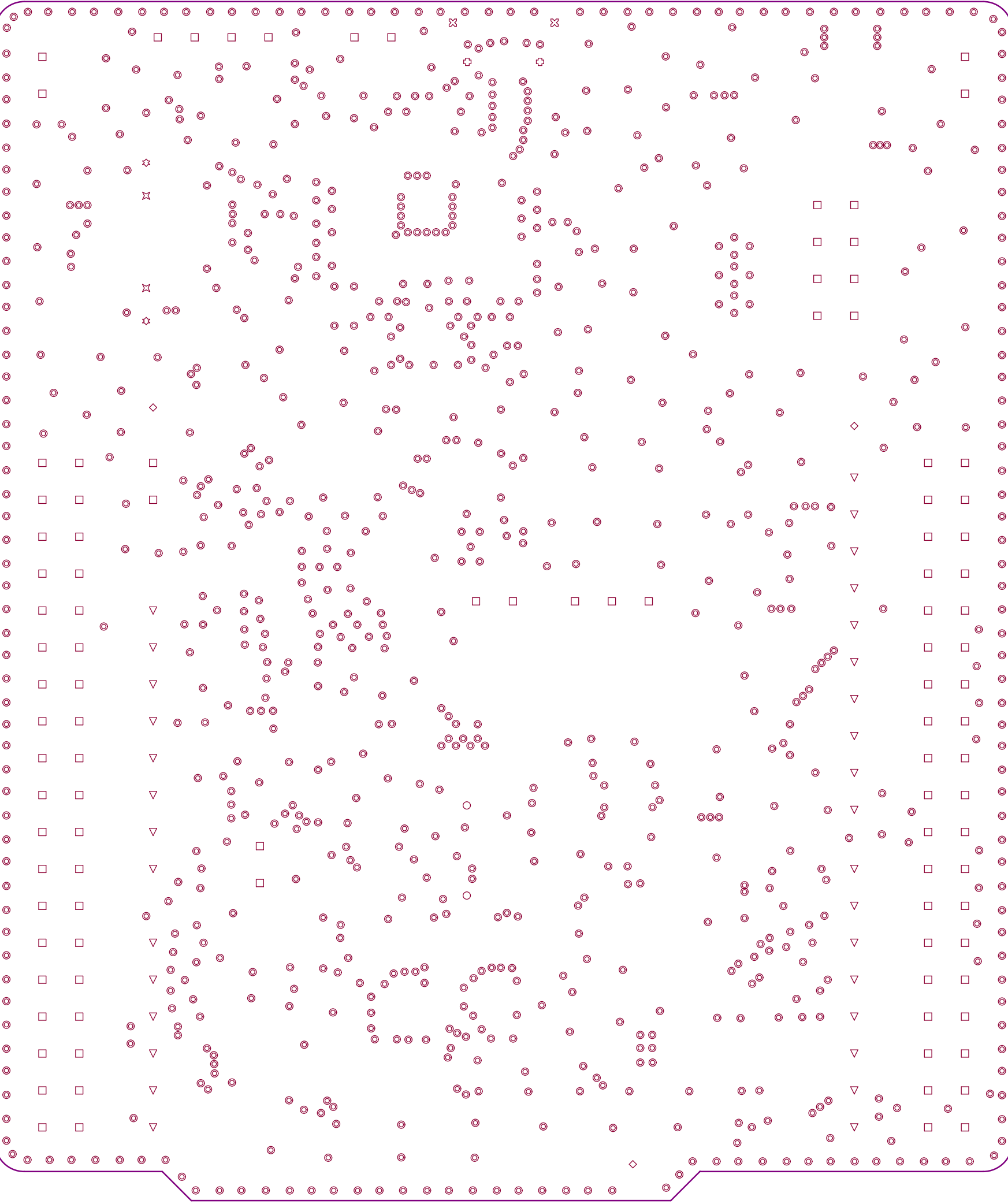
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,015mm	3,5	
3	Top Layer	Copper	0,042mm		
4	Dielectric 1	PP-IT-180A	0,106mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Dielectric 2	FR4	1,248mm	4,2	
7	Signal Layer 2	Copper	0,035mm		
8	Dielectric 3	PP-IT-180A	0,106mm	4,2	
9	Bottom Layer	Copper	0,042mm		
10	Bottom Solder	Solder Resist	0,015mm	3,5	
11	Bottom Overlay				










PCB : TYPE 3

ASPECT-RATIO, AXE Z :  
  
6:1 to 8:1  
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT  
TRACKS : 0.120mm  
GAPS : 0.120mm



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
	920	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
	2	0,600mm (23,62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	1,300mm (51,18mil)	0,700mm (27,56mil)
	2	0,900mm (35,43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
	2	0,970mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
	2	1,000mm (39,37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
	103	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
	32	1,100mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
	2	1,190mm (46,85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
	3	3,200mm (125,98mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
	1068 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

IMPEDANCE TABLE					
LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	0.160	0.226	NA	90 ohm	+/- 10%